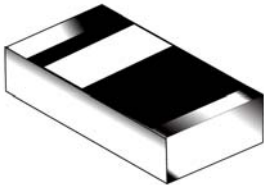


Switching Diode



FEATURES

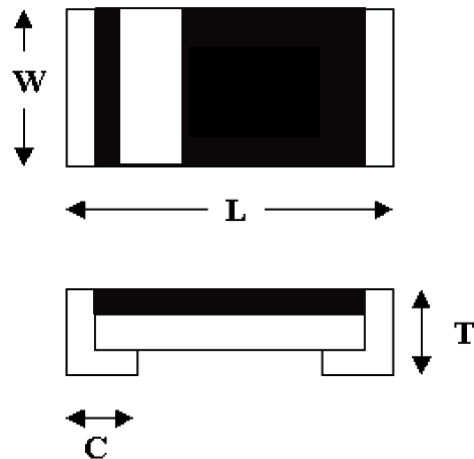
- Silicon epitaxial planar diode
- SMD chip pattern, available in various dimension included 1206 & 0603
- Leadfree and RoHS compliance components
- For small signal switching and operating ambient temperature less than 55°C and voltage withstand less than 60V; not suitable for AC switching input as rectified circuit and high reverse voltage location. BAS216 is suitable for those application

MECHANICAL CHARACTERISTICS

- Size: 0805
- Weight: approx. 6mg
- Marking: Cathode terminal

DIMENSIONS

Dimension/mm	0805
L	2.0±0.2
W	1.25±0.2
T	0.85±0.1
C	0.45±0.2



THERMAL CHARACTERISTICS¹⁾

Parameter at T _{amb} =25°C ¹⁾	Symbol	Value	Unit
Forward Power Dissipation Power derating above 25°C	P _{tot}	200	mW
		1.6	mW/°C
Junction Temperature	T _j	150	°C
Thermal Resistance Junction to Ambient air	R _{θJA}	375	°C/W
Operating& Storage Temperature range	T _{stg}	-55 to 150	°C

1) Valid provided that electrodes are kept at ambient temperature.

MAXIMUM RATING¹⁾

Parameter at $T_{amb}=25^{\circ}C^{1)}$	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	75	V
Average rectified current sin half wave rectification with resistive load	$I_{F(AV)}$	150	mA
Repetitive Peak Forward Current at $T_{amb}=25^{\circ}C$	I_{FRM}	300	mA
Non-Repetitive Surge Forward Current at $t < 1s$ and $T_j=25^{\circ}C$ at $t \leq 8.3ms$ and $T_j=25^{\circ}C$	I_{FSM}	500	mA
		1000	mA

1) Valid provided that electrodes are kept at ambient temperature.

ELECTRICAL CHARACTERISTICS¹⁾

Parameter at $T_{amb}=25^{\circ}C^{1)}$	Symbol	Value	Unit
Forward Voltage at $I_F=10mA$ at $I_F=100mA$	V_F	1.0 <small>MAX</small>	V
		1.25 <small>MAX</small>	V
Leakage Current at $V_R=20V$	I_R	0.025 <small>MAX</small>	μA
Leakage Current at $V_R=75V$		5 <small>MAX</small>	μA
Capacitance at $V_R=0V$, $f=1MHz$	C_{tot}	4 <small>MAX</small>	pF
Reverse Recovery Time at $I_F=I_R=10mA$, $R_L=100\Omega$	t_{rr}	4 <small>MAX</small>	ns

1) Valid provided that electrodes are kept at ambient temperature.

TYPICAL CHARACTERISTICS

Figure 1. Forward Characteristic

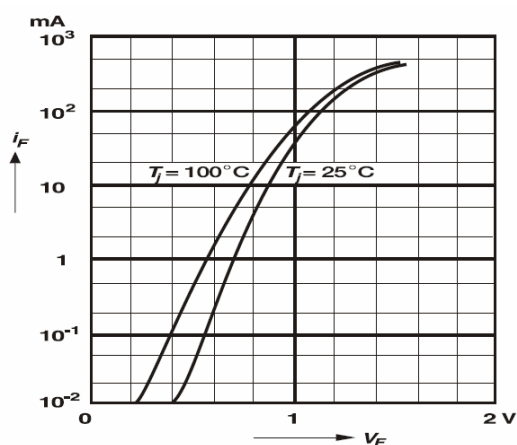


Figure 2. Power De-rating

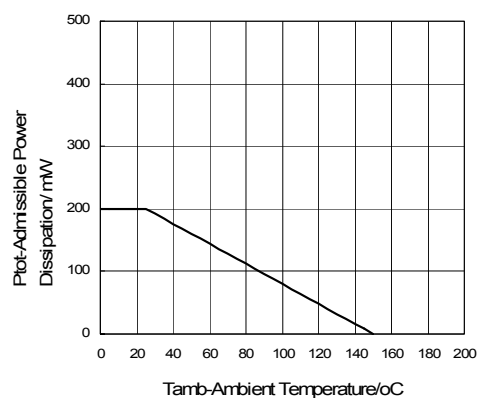


Figure 3. Forward Current De-rating

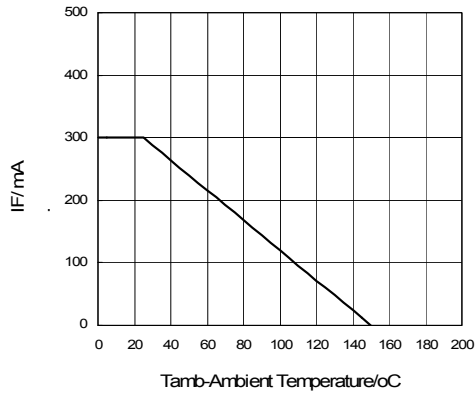
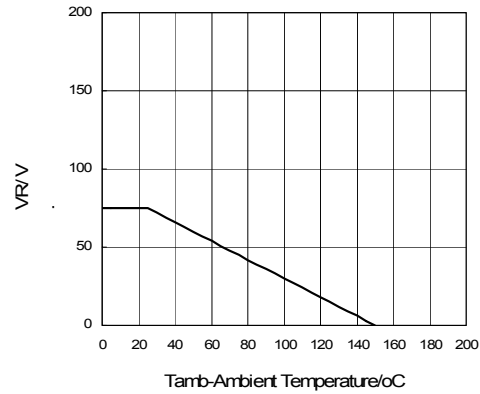


Figure 4. Reverse Voltage De-rating

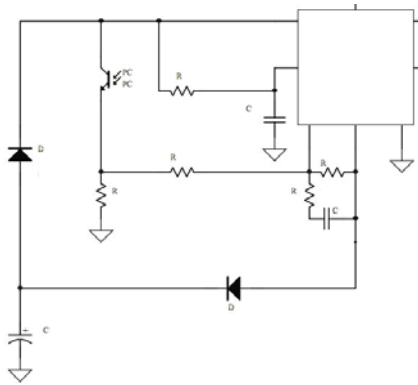


TEST CHARACTERISTICS

Test Item	Test Condition	Requirement
Solderability	Sn bath at 245±5°C for 2±0.5s	>95% area tin covered
Resistance to Soldering Heat	Sn bath at 260±5°C for 10±2s	V _F , V _R & I _R within spec; no mechanical damage
Humidity Steady State	At 85°C 85%RH for 168hrs	V _F , V _R & I _R within spec
Continue Forward Operating Life	At 25°C I _F = 1.1I _F for 1000hrs	V _F , V _R & I _R within spec
Thermal Shock	-55 ±5°C/5min to 150±5°C/5min for 10cycles	V _F , V _R & I _R within spec
Bending Strength	Bending up to 2mm for 1cycle	V _F , V _R & I _R within spec; no mechanical damage

APPLICATIONS

- Function: suit for small signal switching application
- Typical Application circuit:



- Typical Product field: General application except high reverse voltage location

- Soldering Condition:

Soldering Condition & Caution

- Recommended Soldering Condition
(Refer to IPC/JEDEC J-STD-020D 4-1&5.2)

Recommended Profile Condition	Sn-Pb Soldering	Leadfree Soldering	Wave Soldering
Ramp-up rate (from pre-heat stage)	<3°C/s	<3°C/s	ΔT<150°C
Pre-heat Temperature & Time	100-150 °C 60-120s	150-200 °C 60-120s	100-150 °C 60-120s
Soldering Temperature & Time	183 °C 60-150s	217 °C 60-150s	260±5°C 5±2s
Peak Temperature	230±5°C <260°C	245±5°C <260°C	260±5°C
Time within 5°C of peak temperature	10-20s	20-30s	-
Ramp-down rate	<6°C/s	<6°C/s	<6°C/s
Time 25°C to peak temperature	<6min	<8min	-

Manual Soldering: Approx. 350°C for 3s, avoid solder iron tip direct touch the components body

Recommended Soldering Profile

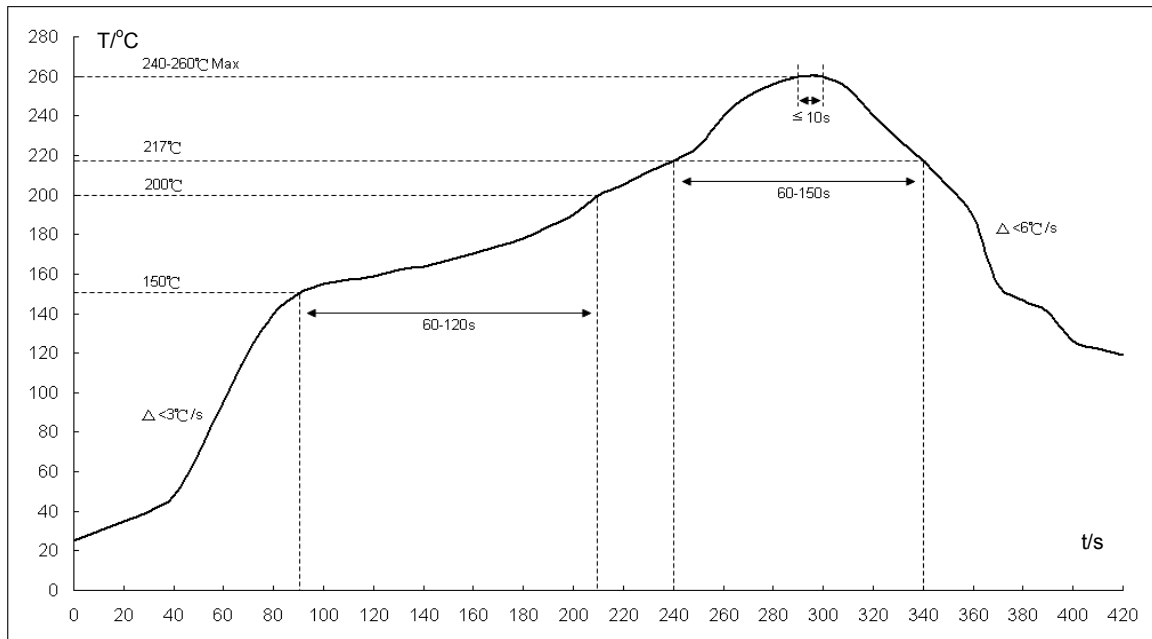


Fig1: Reflow soldering profile for lead-free solder (SnAgCu)

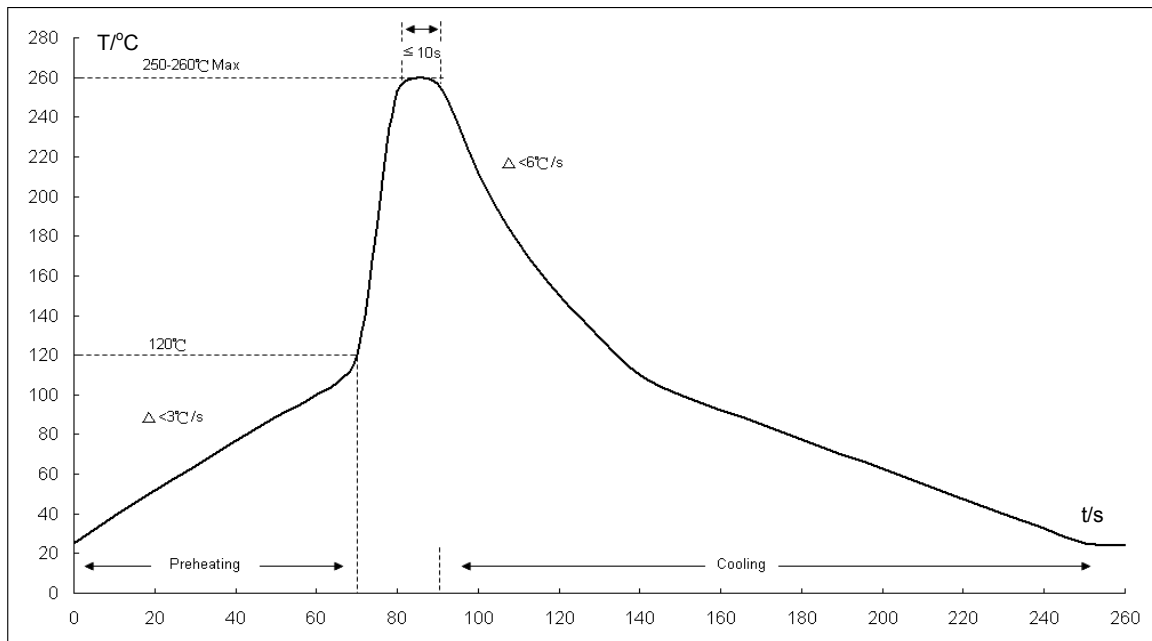
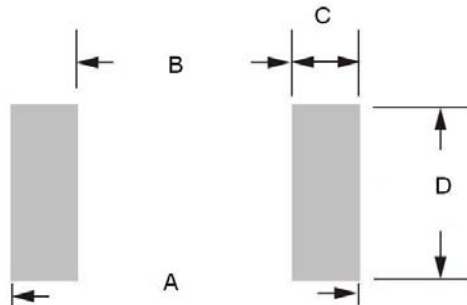


Fig2: Wave soldering profile

- *1. The recommended profiles are referring to IPC/JEDEC J-STD-020D & IEC-60068-2-58
- *2. Chip diodes are able to stand maximum soldering temperature up to 260°C max for 10s, and the soldering cycles with max 3 times, referring to IEC-60068-2-58

■ Recommended Soldering Footprint:



■ Reflow/Wave Soldering

Product Size	Dimension/ mm			
	A	B	C	D
0805	2.6-3.4	1.2	0.7-1.1	1.2-1.4

- Storage Condition: Product termination solderability can degrade due to high temperature and humidity or chemical environment. Storage condition must be in an ambient temperature of <40°C and ambient humidity of <75%RH, and free from chemical.

ENVIRONMENTAL CHARACTERISTICS

Product	Hazardous Substance or Element/ppm					
	Pb	Cd	Hg	Cr ⁶⁺	PBB	PBDE
	<1000	<100	<1000	<1000	<1000	<1000

Product	Halogen Substance/ ppm				
	F	Cl	Br	I	Total
	<900	<900	<900	<900	<1500

PACKING METHOD

Product	Quantity/Reel	Reel Size	Tape
	5,000pcs	7"	Paper